



1765

In re application of: Athavale et al.  
Serial No.: 09/757,123 Group: Art Unit 1765  
Filed: January 9, 2001 Examiner: Brown, Charlotte A.  
For: **METHOD FOR DRY ETCHING DEEP TRENCHES IN A SUBSTRATE**

Assistant Commissioner for Patents  
Washington, D.C. 20231

**AMENDMENT TRANSMITTAL FORM**

Sir:

Transmitted herewith is an amendment in the above-identified application.

- ☐ Small entity status of this application under 37 C.F.R. § 1.9 and 1.27 has been established by a verified statement previously submitted.  
☐ A verified statement to establish small entity under 37 C.F.R. § 1.9 and 1.27 is enclosed.  
☒ No additional fee is required.

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The fee has been calculated as shown below:

	(Col. 1)		(Col. 2)		(Col. 3)	SMALL ENTITY		OTHER THAN SMALL ENTITY	
	CLAIMS REMAINING AFTER AMENDMENT		HIGHEST NO. PREVIOUSLY PAID FOR		PRESENT EXTRA		RATE	ADDIT. FEE	OR RATE
TOTAL	31 *	MINUS	31**	= 0	X	9	\$ 0	X	18
INDEP.	3*	MINUS	3***	= 0	X	42	\$ 0	X	84
<input type="checkbox"/> FIRST PRESENTATION OF MULTIPLE DEP. CLAIM						X	140	\$	X 280
						TOTAL		OR TOTAL	
						ADDIT. FEE		\$ 0	

\*If the entry in Co. 1 is less than entry in Col. 2, write "0" in Col. 3.

\*\*If the "Highest No. Previously Paid for" IN THIS SPACE is less than 20, enter "20".

\*\*\*If the "Highest No. Previously Paid For" IN THIS SPACE is less than 3, enter "3".

The Highest No. Previously Paid For" (Total or indep.) is the highest number found in the appropriate box in Col. 1 of a prior amendment or the number of claims originally filed.

- ☐ Please charge Deposit Account No. \_\_\_\_ in the amount of \$\_\_\_\_. Two (2) copies of this sheet are enclosed.  
☐ Please charge fee of \$\_\_\_\_ for \_\_\_\_\_ by Credit Card Payment Form PTO-2038 enclosed herewith  
☒ Please charge any deficiency as well as any other fee(s) which may become due under 37 C.F.R. § 1.16 and/or 1.17 at any time during the pendency of this application, or credit any overpayment of such fee(s) to Deposit Account No. **50-0679**. Also, in the event any extensions of time for responding are required for the pending application(s), please treat this paper as a petition to extend the time as required and charge Deposit Account No. **50-0679** therefor. **TWO (2) COPIES OF THIS SHEET ARE ENCLOSED.**

Respectfully submitted,

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**CERTIFICATE OF MAILING UNDER 37 C.F.R. § 1.8(a)**

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail, postpaid in an envelope, addressed to the: Assistant Commissioner for Patents, Washington, D.C. 20231 on **January 23, 2003**.

Dated: 1/23/03

Frank V. DeRosa



**PATENT**  
**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

#11/c  
ca  
1/31/03

Applicants: Athavale et al.

Examiner: Brown, Charlotte A.

Serial No: 09/757,123

Group Art Unit: 1765

Filed: January 9, 2001

Docket: 8055-142 (01 P7408 US 01)

For: **METHOD FOR DRY ETCHING DEEP TRENCHES IN A SUBSTRATE**

Commissioner of Patents  
Washington, D.C. 20231

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**AMENDMENT**

This is a response to an Office Action mailed on October 23, 2002. Please amend the application as follows:

**In The Claims:**

1. (Thrice Amended) A method for etching deep trenches in a substrate, comprising the steps of:
- securing a wafer to an electrode in a plasma chamber, the wafer comprising a silicon substrate;
  - heating the wafer to a temperature of greater than 200 degrees Celsius; and
  - exposing the wafer to a reactive plasma to etch deep trenches into the silicon substrate of the wafer, wherein the deep trenches have a depth of about 8um or greater and wherein the deep trench etching is performed for a ground rule design of 175nm or less.

**CERTIFICATE OF MAILING 37 C.F.R. § 1.8(a)**

I hereby certify that this correspondence (and any document referred to as being attached or enclosed) is being deposited with the United States Postal Service as first class mail, postage paid in an envelope addressed to: Commissioner of Patents, Washington, D.C. 20231 on January 23, 2003.

Dated: 1/23/03

Frank V. DeRosa